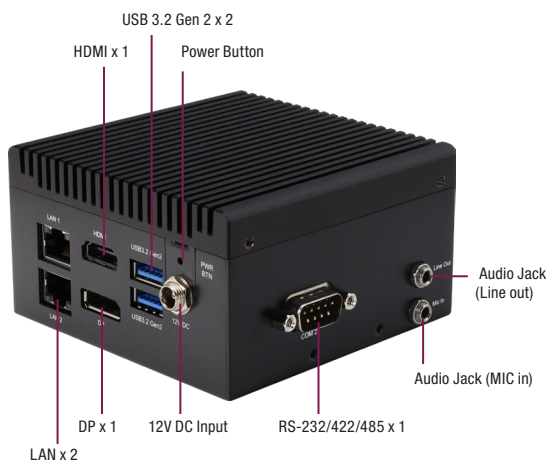


UP Squared TWL Edge

UP Squared TWL system with Intel® Processor N-series SoC (formerly Twin Lake)

Front View



Rear View



Features

- Intel® Processor N-series SoC (formerly Twin Lake)
- Onboard LPDDR5 Memory up to 16GB
- Onboard eMMC Storage up to 128GB
- Gb Ethernet (full speed) RJ-45 x 2
- USB 3.2 Type A x 3
- DP 1.2 / HDMI 2.0b / eDP 1.3 x 1
- RS232/422/485 x 2
- M.2 2230 E-Key x 1
- M.2 2280 M-Key x 1
- TPM 2.0
- 12V DC-in
- CE-RED Certified



Specifications

System	
CPU	Intel® Core™ 3 Processor N355 Intel® Processor N250 Intel® Processor N150 (formerly Twin Lake)
Memory	Up to 16GB LPDDR5
Graphics	Intel® UHD Graphics for 12th Gen Intel® Processors
Storage	Up to 128GB eMMC
Ethernet	Gb Ethernet (full speed) RJ-45 x 2
WiFi/BT	M.2 2230 E-key x 1 (Optional: Intel® Wi-Fi 6E AX210 module)
Expansion Slot	M.2 2230 E-Key x 1 (PCIe x1, USB2.0 x1) M.2 2280 M-key x 1 (PCIe x2)
Security	Onboard TPM 2.0
OS Support	Windows® 11 LTSC Ubuntu: 24.04 LTS Yocto: 5.1
I/O Placements	
USB	USB 2.0 x 2 (via 10 Pin Header x 1) USB 3.2 Gen 2 x 3 (Type-A)
Display Port	HDMI 2.0b x 1 DP 1.2 x 1
Ethernet	Gb Ethernet (full speed) RJ-45 x 2
COM	RS-232/422/485 x 2
Audio	Line out x 1 Mic in x 1
GPIO	—
Power Supply	
Power requirement	12V DC-in, 5A
Power supply type	AT/ATX
Power Consumption (Typical)	15W~37W
Mechanical	
Mounting	VESA Mounting
Dimensions (WxHxD)	3.74" x 3.74" x 2.16" (95 x 95 x 55 mm)
Net Weight	0.99lb (450g)
Gross Weight	1.32lb (600g)
Environment	
Operating Temperature	-4°F ~ 140°F (-20°C ~ 60°C) / 0.7 airflow
Operating Humidity	0% ~ 90% relative humidity, non-condensing
Storage Temperature	-4°F ~ 158°F (-20°C ~ 70°C)
MTBF	1,224,238
Certification	CE/FCC Class A, RoHS Compliant, REACH

